

Claims

[c1] 1. A solder paste printing method comprising:
a first process for mounting a mask having apertures corresponding to land portions of a printed circuit board, on said printed circuit board at a predetermined position thereof in a state where it is placed in position;
a second process for mounting a solder paste containing therein as a solder material a tin-zinc (Sn-Zn) system solder on said mask and for permitting said solder paste to make rolling from one end of said mask toward the opposite end thereof by means of a squeegee, while maintaining moisture contained in the atmosphere surrounding said solder paste at a value equal to or less than a predetermined value, wherein said squeegee urges said solder paste to make rolling, to thereby fill said solder paste into said apertures; and
a third process for separating said mask away from said printed circuit board.

[c2] 2. The solder paste printing method according to claim 1, wherein said moisture is equal to or less than 10 g/m³.

[c3] 3. The solder paste printing method according to claim 2, wherein said atmosphere mainly comprises a nitrogen gas (N₂).

[c4] 4. A solder paste printing apparatus comprising:
a mask having apertures corresponding to land portions of a printed circuit board;
a squeegee urging a solder paste containing therein as a solder material a tin-zinc (Sn-Zn) system solder and mounted on said mask, which is placed in position at a predetermined position on said printed circuit board to make rolling from one end of said mask toward the opposite end thereof; and
a moisture regulating means for maintaining moisture contained in the atmosphere surrounding said solder paste at a value equal to or less than a predetermined value.

[c5] 5. The solder paste printing apparatus according to claim 4, wherein said moisture is equal to or less than 10 g/m³.

[c6] 6. The solder paste printing apparatus according to claim 5, wherein said

atmosphere mainly comprises a nitrogen gas (N_2).

[c7]